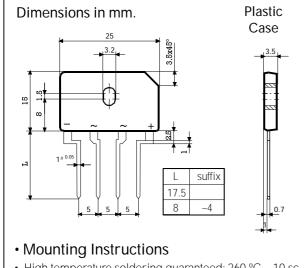


## 4 Amp. Glass Passivated Bridge Rectifier



- High temperature soldering guaranteed: 260 °C 10 sc.
- Recommended mounting torque: 8 Kg.cm.

Voltage Current 50 to 1000 V. 4.0 A.



- · Glass Passivated Junction Chips.
- UL recognized under component index file number E130180.
- · Lead and polarity identifications.
- · Case: Molded Plastic.
- Ideal for printed circuit board (P.C.B.).
- · High surge current capability.
- The plastic material carries U/L recognition 94 V-O.

## Maximum Ratings, according to IEC publication No. 134

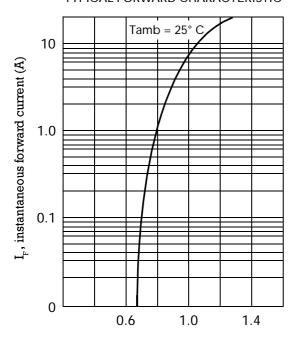
		FBI4A 5M1	FBI4B 5M1	FBI4D 5M1	FBI4G 5M1	FBI4J 5M1	FBI4K 5M1	FBI4M 5M1
$V_{RRM}$	Peak recurrent reverse voltage (V)	50	100	200	400	600	800	1000
V <sub>RMS</sub>	Maximum RMS voltage (V)	35	70	140	280	420	560	700
I <sub>F(AV)</sub>	Max. Average forward current with heatsink without heatsink	4.0 A at 100 °C 3.0 A at 40 °C						
IFSM	8.3 ms. peak forward surge current	150 A						
l <sup>2</sup> t	Rating for fusing (t<8.3 ms.)	93 A <sup>2</sup> sec						
V <sub>DIS</sub>	Dielectric strength (terminals to case, AC 1 min.)	1500 V						
T <sub>j</sub>	Operating temperature range	– 55 to + 150 °C						
T <sub>stg</sub>	Storage temperature range	− 55 to +150 °C						

### Electrical Characteristics at Tamb = 25°C

V <sub>F</sub>	Max. forward voltage drop per element at $I_F = 4 \text{ A}$	1.0V
I <sub>R</sub>	Max. reverse current per element at $V_{\mbox{\tiny RRM}}$	5μΑ
	MAXIMUM THERMAL RESISTANCE	
R <sub>th (j-c)</sub>	Junction-Case. With Heatsink.	5 °C/W
R <sub>th (i-a)</sub>	Junction-Ambient. Without Heatsink.	22 °C/W

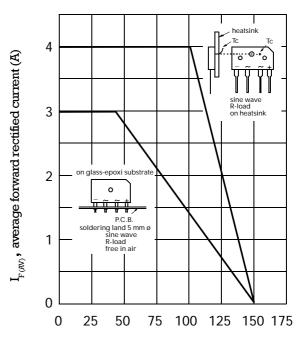


#### TYPICAL FORWARD CHARACTERISTIC



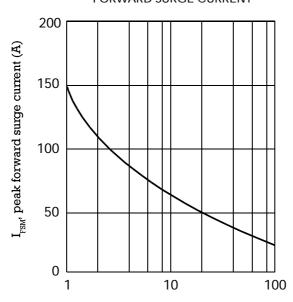
 $V_{_{\rm F}}$ , instantaneous forward voltage (V)

#### FORWARD CURRENT DERATING CURVE



Tamb, ambient temperature (°C)

# MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT



Number of cycles at 60 Hz.